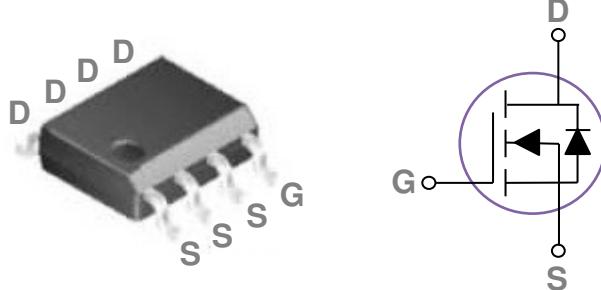


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOP8 Pin Configuration



BVDSS	RDS(ON)	ID
40V	9mΩ	9A

### Features

- 40V, 9A,  $RDS(ON)=9m\Omega @ VGS = 10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

### Applications

- Notebook
- Load Switch
- LED applications
- Hand-Held Device

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_A=25^\circ C$ )	9	A
	Drain Current – Continuous ( $T_A=100^\circ C$ )	5.7	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	36	A
$P_D$	Power Dissipation ( $T_A=25^\circ C$ )	1.47	W
	Power Dissipation – Derate above 25°C	0.012	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62.5	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_D=250\mu\text{A}$	40	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $\text{I}_D=1\text{mA}$	---	0.03	---	$\text{V}/^\circ\text{C}$
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=40\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$\text{V}_{\text{DS}}=32\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=85^\circ\text{C}$	---	---	10	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_D=8\text{A}$	---	7	9	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_D=4\text{A}$	---	9.5	13	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$ , $\text{I}_D=250\mu\text{A}$	1.2	1.8	2.5	V
			---	-5	---	$\text{mV}/^\circ\text{C}$
$\text{gfs}$	Forward Transconductance	$\text{V}_{\text{DS}}=10\text{V}$ , $\text{I}_D=10\text{A}$	---	13	---	S

**Dynamic and switching Characteristics**

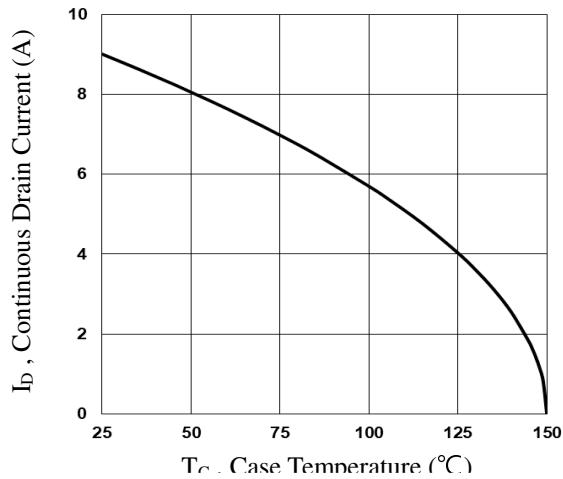
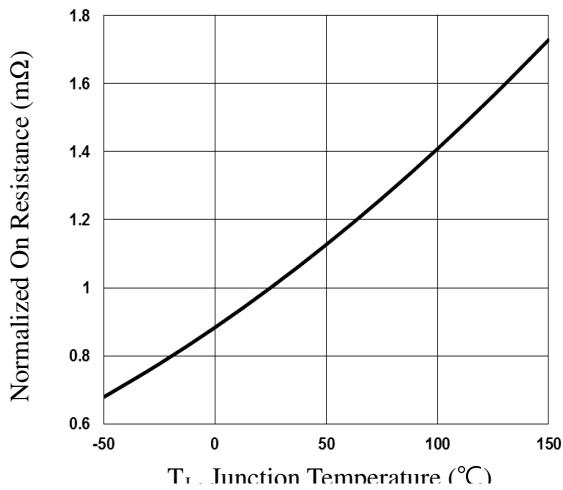
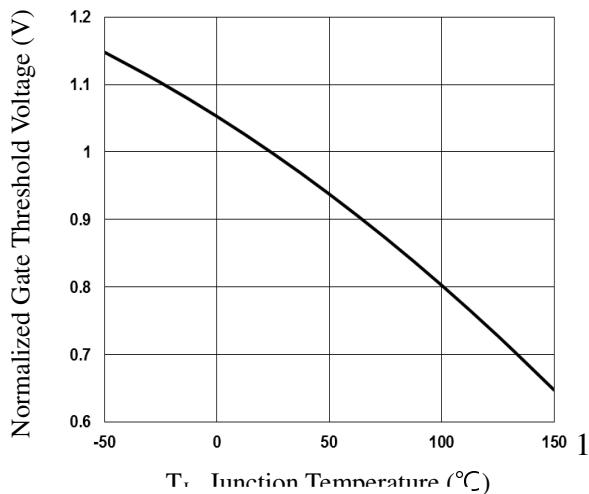
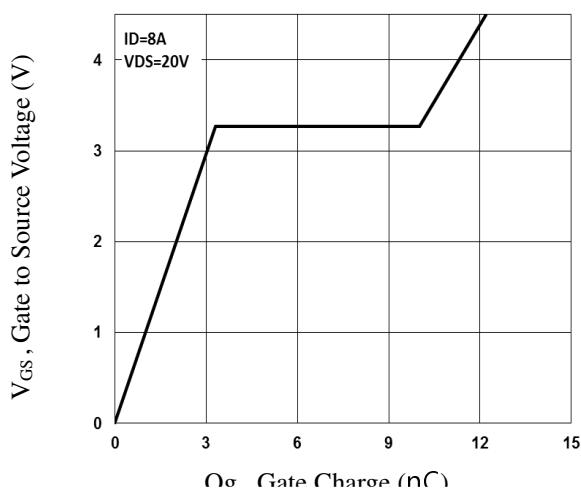
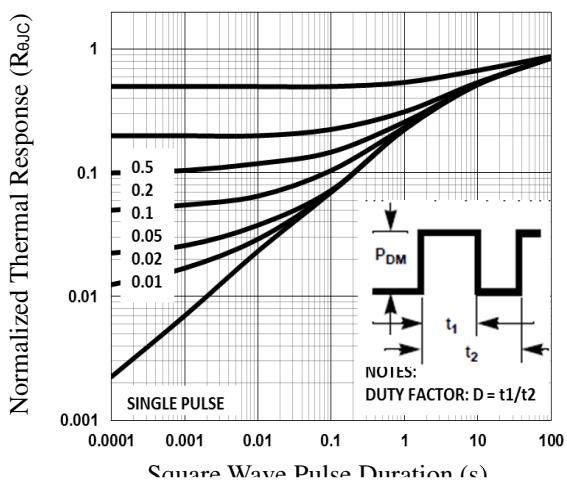
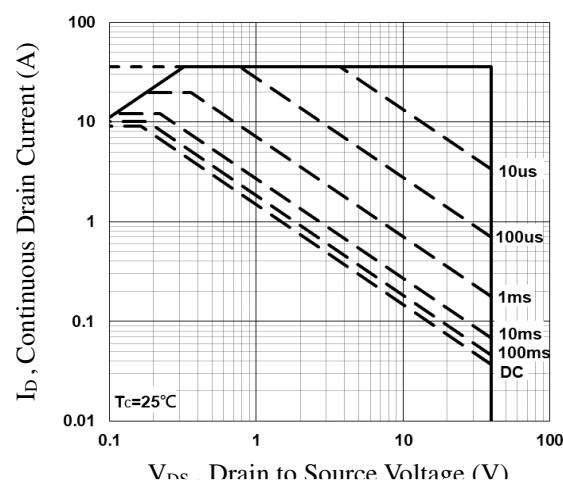
$\text{Q}_g$	Total Gate Charge <sup>2, 3</sup>	$\text{V}_{\text{DS}}=20\text{V}$ , $\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_D=8\text{A}$	---	12.2	24	nC
$\text{Q}_{\text{gs}}$	Gate-Source Charge <sup>2, 3</sup>		---	3.3	7	
$\text{Q}_{\text{gd}}$	Gate-Drain Charge <sup>2, 3</sup>		---	6.7	13	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time <sup>2, 3</sup>	$\text{V}_{\text{DD}}=15\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{R}_G=3.3\Omega$ $\text{I}_D=1\text{A}$	---	13.2	25	ns
$\text{T}_r$	Rise Time <sup>2, 3</sup>		---	2.2	5	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time <sup>2, 3</sup>		---	72	130	
$\text{T}_f$	Fall Time <sup>2, 3</sup>		---	4.5	10	
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{DS}}=25\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $\text{F}=1\text{MHz}$	---	1220	2200	pF
$\text{C}_{\text{oss}}$	Output Capacitance		---	130	250	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		---	55	110	
$\text{R}_g$	Gate resistance	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$ , $\text{F}=1\text{MHz}$	---	2.2	---	$\Omega$

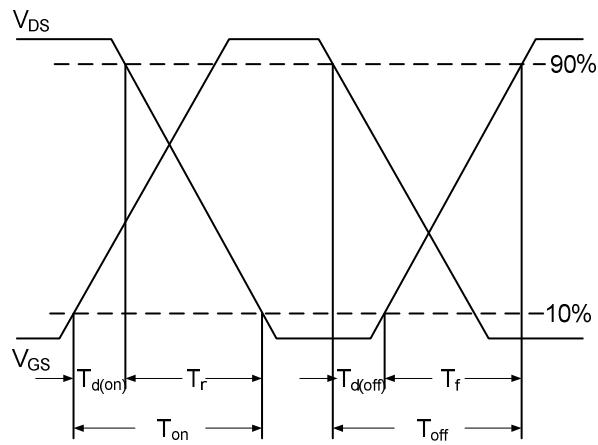
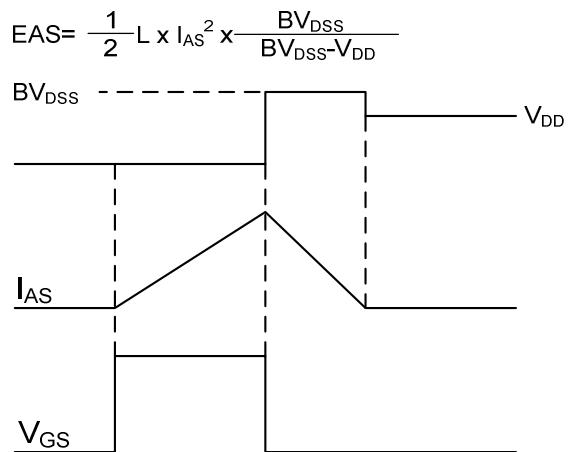
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{I}_s$	Continuous Source Current	$\text{V}_G=\text{V}_D=0\text{V}$ , Force Current	---	---	15	A
			---	---	30	A
$\text{V}_{\text{SD}}$	Diode Forward Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$\text{t}_{\text{rr}}$	Reverse Recovery Time <sup>3</sup>	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_s=1\text{A}$ , $d\text{I}/dt=100\text{A}/\mu\text{s}$	---	17	---	ns
			---	2.8	---	nC

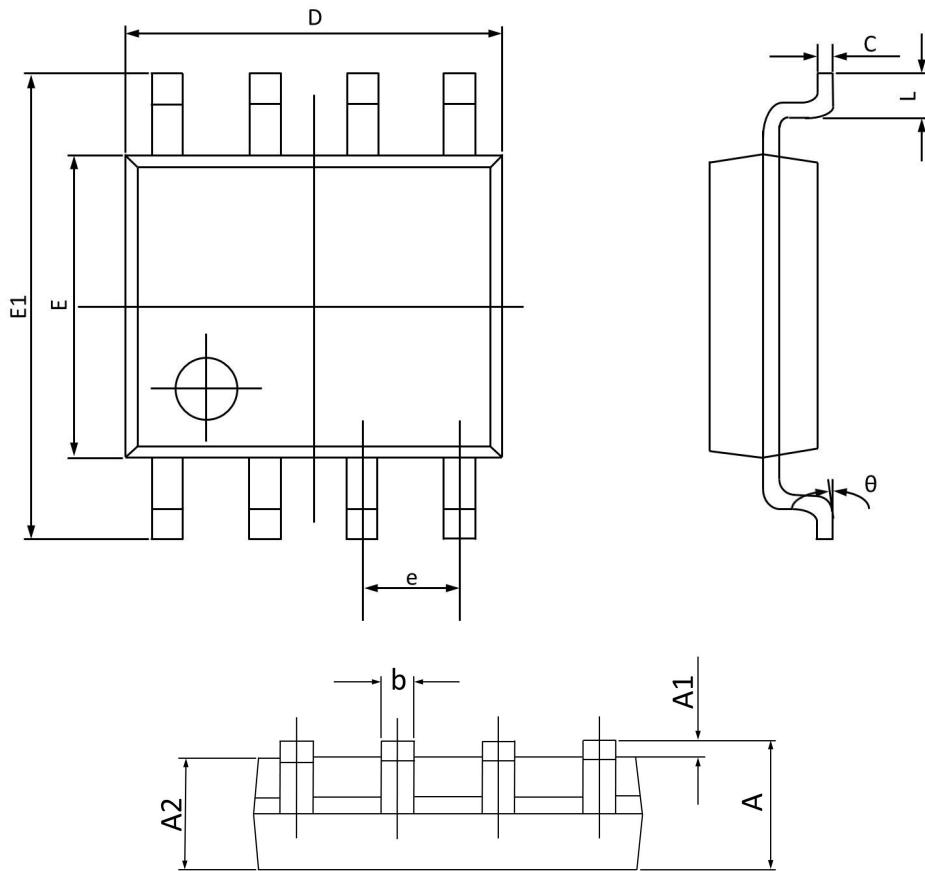
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs.  $T_C$** 

**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$** 

**Fig.3 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**


**Fig.7** Switching Time Waveform

**Fig.8** EAS Waveform

## SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.750	1.350	0.069	0.053
A1	0.250	0.100	0.010	0.004
A2	1.500	1.300	0.059	0.051
b	0.490	0.350	0.019	0.014
C	0.260	0.190	0.010	0.007
D	5.100	4.700	0.201	0.185
E	4.100	3.700	0.161	0.146
E1	6.200	5.800	0.244	0.228
e	1.27BSC		0.05BSC	
L	0.900	0.400	0.035	0.016
θ	8°	0°	8°	0°